

WHAT IS CLAIMED IS

1. A circuit board having circuit wires on the surface and back surface thereof, comprising lands having through holes through which conductive members of electrical parts are inserted, said through holes being coated with  
5 a conductive film on the side surfaces themselves,

wherein said lands and conductive members are mounted by using lead-free solder and the width of each land corresponding to the difference between the radius of each land and each through hole is set at 0.40 mm or more.

10 2. A circuit board having circuit wires on the surface and back surface thereof, comprising lands having through holes through which conductive members of electrical parts are inserted, said through holes being coated with a conductive film on the side surfaces themselves,

15 wherein said lands and conductive members are mounted by using lead-free solder, and the width of each land corresponding to the difference between the radius of each land and each through hole is set such a value that the intimate contact strength of said land is larger than the land exfoliating force.

20 3. The circuit board as claimed in claim 1, wherein each fillet of the lead-free solder is formed on each land and between each land and each conductive member.

4. The circuit board as claimed in claim 2, wherein each fillet of the lead-free solder is formed on each land and between each land and each conductive member.

25 5. The circuit board as claimed in claim 1, wherein the lead-free solder

contains tin-zinc based solder, tin-silver based solder or tin-copper based solder.

6. The circuit board as claimed in claim 2, wherein the lead-free solder contains tin-zinc based solder, tin-silver based solder or tin-copper based solder.

7. The circuit board as claimed in claim 1, wherein said lands are arranged with 1 to 5 mm pitch.

8. The circuit board as claimed in claim 2, wherein said lands are arranged with 1 to 5 mm pitch.

9. The circuit board as claimed in claim 1, wherein each of said electronic parts has one or more conductive member lines in which each line has two or more conductive members arranged to make a line.

10. The circuit board as claimed in claim 2, wherein each of said electronic parts has one or more conductive member lines in which each line has two or more conductive members arranged to make a line.

11. The circuit board as claimed in claim 9, wherein said each electronic part is a IC, a IC socket or a connector.

12. The circuit board as claimed in claim 10, wherein said each electronic part is a IC, a IC socket or a connector.

13. Electronic equipment, in which electrical parts are inserted to and mounted on said circuit board of claim 1 by using the lead-free solder.

14. Electronic equipment, in which electrical parts are inserted to and mounted on said circuit board of claim 2 by using the lead-free solder.